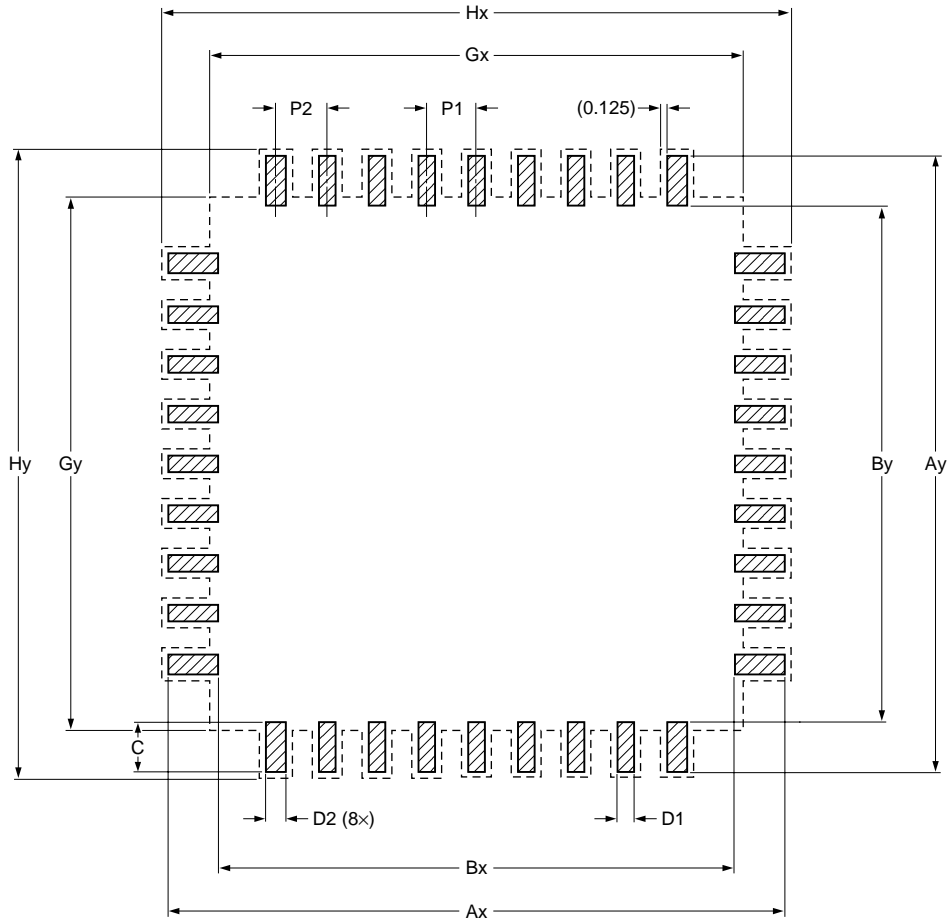



Footprint information for reflow soldering of LQFP64 package

SOT791-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	17.300	17.300	14.300	14.300	1.500	0.500	0.600	14.500	14.500	17.550	17.550